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## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

## Listing of Claims:

1. A method for processing integrated circuit devices including a water recycling process, the process comprising:

operating a chemical mechanical planarization process, the chemical mechanical planarization process including a discharge for process water, the process water being used to process one or more semiconductor wafers;

selectively discharging process water from the discharge;

transferring the process water from the chemical mechanical planarization process to a facility process; and

using the discharged water in the facility process;

wherein the facility process is selected from at least a cooling tower and/or a local scrubber.

- 2. (Canceled)
- 3. The method of claim 1 wherein the discharge water is characterized by a pH value ranging from about 6 to about 10.
- 4. The method of claim 1 wherein the discharge water is characterized by a conductivity is less than about 2000  $\mu$  siemens per centimeter.
- 5. The method of claim 1 wherein the selectively discharging is provided using a control valve coupled to the discharge, the control valve being coupled to computer hardware.
- 6. The method of claim 1 wherein the discharge includes a plurality of lines, each of the lines being coupled to one or more processing stations.

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- 7. The method of claim 1 wherein the transferring to the facility process comprises transferring to a collection tank before transferring the discharge water to the facility process.
- 8. The method of claim 1 wherein the selectively discharging comprises outputting a signal in response to process in computer software to open a value to release the process water.
- 9. The method of claim 1 wherein the process water is ultra-pure water having a resistivity of about 18 Mega-ohms.
- 10. The method of claim 1 wherein the transferring of the process water from the chemical mechanical planarization process to a facility process occurs free from any chemical treatment between the chemical mechanical planarization process and the facility process.
- 11. (Currently Amended) A method for processing integrated circuit devices including a water recycling process, the process comprising:

operating a chemical mechanical polishing process using an incoming stream of ultra-pure water, the chemical mechanical polishing process including a discharge for used ultra-pure water;

using the ultra-pure water [being used to process] to clean one or more semiconductor wafers while a flow of any chemical species have been stopped to the one or more semiconductor wafers, the used ultra-pure water [and discharged through the discharge to form] forming a facility water;

selectively discharging the facility water from the discharge of the chemical mechanical polishing process and transferring the facility water from the discharge of the chemical mechanical polishing process to a facility process, the <u>discharged process water</u>

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[transferring] being free from any chemical treatment from the discharge to the facility process [of the discharged process water]; and

using the discharged process water in the facility process.

- 12. The method of claim 11 wherein selectively discharging is provided by a valve coupled to the chemical mechanical planarization process.
- 13. The method of claim 11 wherein the ultra-pure water is characterized by a resistance of about 18 mega-ohm.
- 14. The method of claim 13 wherein the ultra-pure water is substantially free from particles greater than about 0.05 microns in dimension.
- 15. The method of claim 11 wherein the transferring the facility water from the discharge of the chemical mechanical polishing process to a facility process includes storing the facility water in a storage facility before use by the facility process.
- 16. The method of claim 15 wherein the facility process is selected from a cooling process, a scrubbing process.
- 17. (Currently Amended) A system for chemical mechanical polishing, the system comprising:

a plurality of processing stations, each of the processing stations being configured to perform at least one processing operation;

a discharge line coupled to one or more of the processing stations to receive discharge water;

a first valve coupled to a chemical input line to introduce chemical species to one or more of the processing stations;

a second valve coupled to an ultra-pure water line to introduce ultra-pure water to at least one or more of the processing stations;

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a third valve coupled to the discharge line to selectively output the discharge water for use in a facility process while the first valve for introducing chemical species to one at least one or more of the processing stations is closed; and

a drain line coupled to the discharge line for outputting the discharge water to a drain;

whereupon the discharge water is substantially used ultra-pure water free used for a rinse process associated with one or more of the processing stations.

- 18. The system of claim 17 further comprising a computer system coupled to the valve, the computer system including one or more memories, the one or more memories including a first code directed to actuate the value to output the discharge water for use in the facility process.
- 19. The system of claim 17 wherein the discharge line comprises a plurality of lines.
- 20. The system of claim 17 further comprising a source line for ultra-pure water coupled to one or more of the processing stations, the ultra-pure water being discharge water after being used by one or more of the processing stations.
- 21. (New) A method for processing semiconductor wafers, the method comprising:

introducing ultra-pure water into a chemical clean process for semiconductor wafers in a chemical mechanical polishing tool;

processing the semiconductor wafers using the ultra-pure water and selected chemical species;

transferring the used water including the ultra-pure water and the selected chemical species to a drain for recycling or removal;

stopping flow of the chemical species; rinsing the semiconductor wafers using the ultra-pure water;

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transferring the used ultra-pure water to a facility line; using the used ultra-pure water in a facility process.

22. (New) The method of claim 21 wherein the facility process is selected from a cooling process or a scrubber process.